



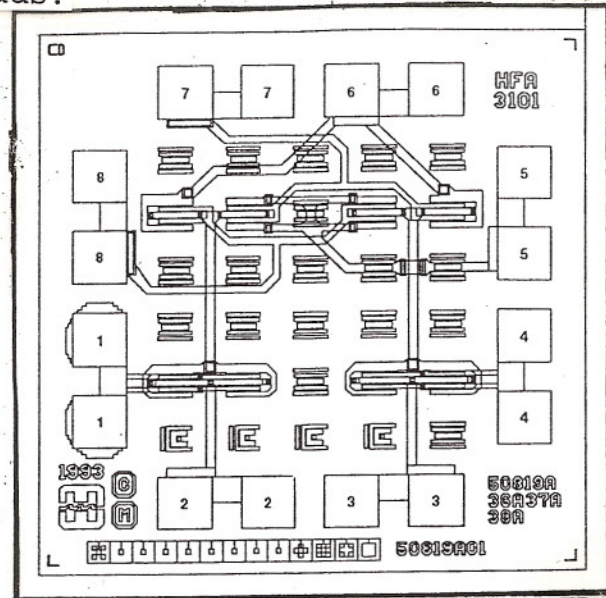
# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

NOTE: All bond pads are double bond pads.



Pad    Function

- 1    Base Q5
- 2    Emitter Q5
- 3    Emitter Q6
- 4    Base Q6
- 5    Collector Q2 and Collector Q4
- 6    Collector Q1 and Collector Q3
- 7    Base Q2 and Base Q3
- 8    Base Q1 and Base Q4

E & O E. The supply of dice to this layout can only be guaranteed if it forms part of a specification or the chip identification, where given below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the potential to which the chip back must be connected when specifically stated in a NOTE above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. 1 mil. = 0.001 inch. Tolerances on dimensions +/- 3 mils.

**Topside Metal: Al**

**Backside: Si**

**Backside Potential:**

**Mask Ref:**

**Bond Pads : .004" min**

**APPROVED BY: CD**

**MFG: Harris**

**DIE SIZE : .053" x .052"**

**THICKNESS: .014"**

**DATE: 2/5/01**

**P/N: HFA3101Y**